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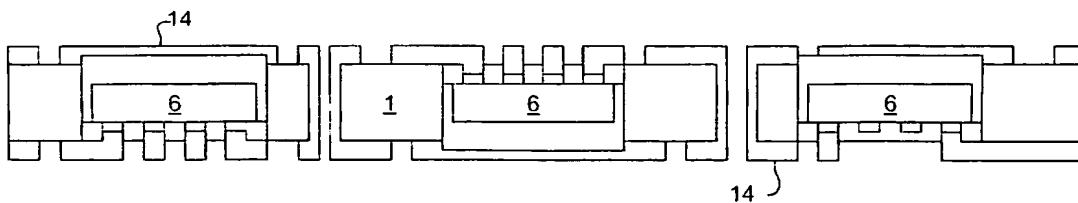
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(54) Title: METHOD FOR MANUFACTURING AN ELECTRONIC MODULE



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(57) Abstract: This publication discloses a method for manufacturing an electronic module, in which manufacture commences from an insulating-material sheet (1). At least one recess (2) is made in the sheet (1) and extends through the insulating-material layer (1) as far as the conductive layer on the opposite surface (1 a). A component (6) is set in the recess, with its contact surface towards the conductive layer and the component (6) is attached to the conductive layer. After this, a conductive pattern (14) is formed from the conductive pattern closing the recess, which is electrically connected from at least some of the contact areas or contact protrusions of the component (6) set in the recess.